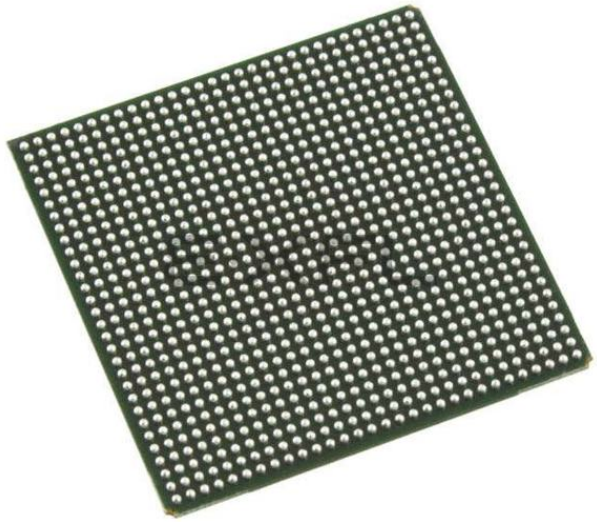

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	8375
Number of Logic Elements/Cells	67000
Total RAM Bits	4642816
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m70se-5fn900i

LatticeECP2/M Family Data Sheet DC and Switching Characteristics

September 2013 Data Sheet DS1006

Absolute Maximum Ratings[1, 2, 3]

Supply Voltage V_{CC} . . . . . -0.5 to 1.32V

Supply Voltage V_{CCAUX} . . . . . -0.5 to 3.75V

Supply Voltage V_{CCJ} . . . . . -0.5 to 3.75V

Output Supply Voltage V_{CCIO} . . . . . -0.5 to 3.75V

Input or I/O Tristate Voltage Applied[4]. . . . . -0.5 to 3.75V

Storage Temperature (Ambient) . . . . . -65 to 150°C

Junction Temperature (Tj) . . . . . +125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[7]

Symbol	Parameter	Min.	Max.	Units
V_{CC}[1, 4, 5]	Core Supply Voltage	1.14	1.26	V
V_{CCAUX}[1, 3, 4, 5]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCPLL}	PLL Supply Voltage	1.14	1.26	V
V_{CCIO}[1, 2, 4]	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ}[1]	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	°C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	°C
SERDES External Power Supply (For LatticeECP2M Family Only)				
V_{CCIB}	Input Buffer Power Supply (1.2V)	1.14	1.26	V
	Input Buffer Power Supply (1.5V)	1.425	1.575	V
V_{CCOB}	Output Buffer Power Supply (1.2V)	1.14	1.26	V
	Output Buffer Power Supply (1.5V)	1.425	1.575	V
$V_{CCAUX33}$	Termination Resistor Switching Power Supply	3.135	3.465	V
V_{CCRX}[6]	Receive Power Supply	1.14	1.26	V
V_{CCTX}[6]	Transmit Power Supply	1.14	1.26	V

Symbol	Parameter	Min.	Max.	Units
V_{CCP}[6]	PLL and Reference Clock Buffer Power	1.14	1.26	V

1. If V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX}. V_{CCPLL} must be connected to the same power supply as V_{CC} through careful filtering and decoupling.
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CCAUX} ramp rate must not exceed 30mV/µs during power-up when transitioning between 0V and 3.3V.
4. For proper power-up configuration, users must ensure that the configuration control signals such as the CFGx, INITN, PROGRAMN and DONE pins are driven to the proper logic levels when the device powers up. The device power-up is triggered by the last of V_{CC}, V_{CCAUX} or V_{CCIO8} supplies that reaches its minimum valid levels. Alternatively, if the configuration control signals are pulled up by V_{CCIO8}, the V_{CCIO8} (configuration I/O bank) voltage must be powered up prior to or at the same time as the last of VCC or VCCAUX reaches its minimum levels.
5. For power-up, V_{CC} must reach its valid minimum value before powering up V_{CCAUX} (LatticeECP2/M “S” version devices only).
6. V_{CCRX},V_{CCTX} and V_{CCP} must be tied together in each quad and all quads need to be powered up.
7. For more power supply design recommendations, refer to TN1114 Electrical Recommendations for Lattice SERDES.

Hot Socketing Specifications[1, 2, 3, 4]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O leakage current	$0 \le V_{IN} \le V_{IH}$ (MAX.)	—	—	+/-1000	µA
I_{HDIN}[5]	SERDES average input current when device is powered down and inputs are driven		—	—	4	mA

1. V_{CC}, V_{CCAUX} and V_{CCIO} should rise/fall monotonically. V_{CC} and V_{CCPLL} must be connected to the same power supply (applies to ECP2-6, ECP2-12 and ECP2-20 only).
2. $0 \le V_{CC} \le V_{CC}$ (MAX), $0 \le V_{CCIO} \le V_{CCIO}$ (MAX) or $0 \le V_{CCAUX} \le V_{CCAUX}$ (MAX).
3. I_{DK} is additive to I_{PU}, I_{PW} or I_{BH}.
4. LVCMOS and LVTTL only.
5. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed V_{CCIB} of 1.575V, 8b10b data and internal AC coupling.

ESD Performance

Please refer to LatticeECP2/M Product Family Qualification Summary for complete qualification data, including ESD performance.

LatticeECP2 Initialization Supply Current[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5, 6, 7]	Units
I_{CC}	Core Power Supply Current	ECP2-6	34	mA
		ECP2-12	54	mA
		ECP2-20	82	mA
		ECP2-35	135	mA
		ECP2-50	187	mA
		ECP2-70	267	mA
I_{CCAUX}	Auxiliary Power Supply Current	ECP2-6	30	mA
		ECP2-12	30	mA
		ECP2-20	30	mA
		ECP2-35	30	mA
		ECP2-50	30	mA
		ECP2-70	30	mA
I_{CCGPLL}	GPLL Power Supply Current (per GPLL)	ECP2-35, -50, -70 Only	0.5	mA
I_{CCSPLL}	SPLL Power Supply Current (per SPLL)	ECP2-35, -50, -70 Only	0.5	mA
I_{CCIO}	Bank Power Supply Current (per Bank)	All Devices	3	mA
I_{CCJ}	VCCJ Power Supply Current	All Devices	4	mA

1. Until DONE signal is active.
2. For further information about supply current, please see the list of additional technical documentation at the end of this data sheet.
3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
4. Frequency 0MHz.
5. T_J = 25°C, power supplies at nominal voltage.
6. A specific configuration pattern is used that scales with the size of the device; consists of 75% PFU utilization, 50% EBR, and 25% I/O configuration.
7. Values shown in this column are the typical average DC current during configuration. Use the Power Calculator tool to find the peak startup current.

RSDS

The LatticeECP2/M devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Signaling)

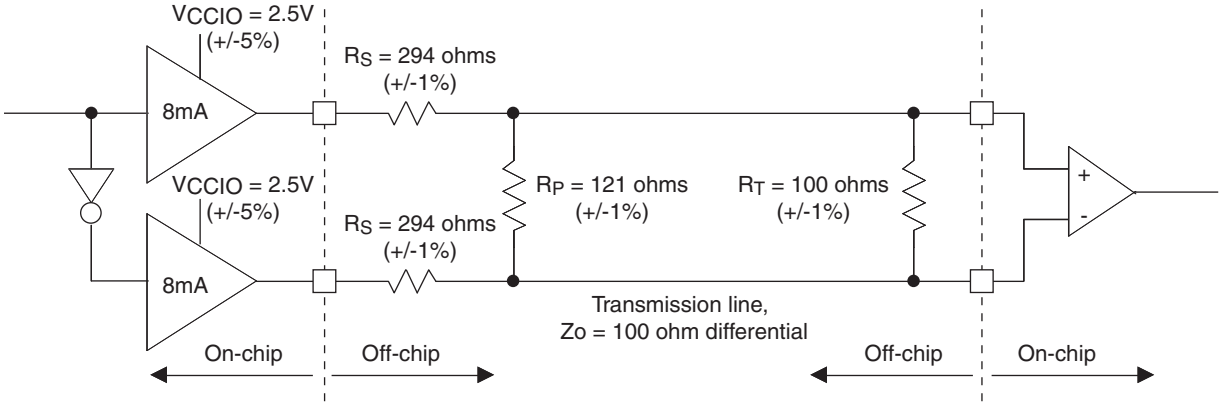


Table 3-5. RSDS DC Conditions[1]

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
V_{CCIO}	Output Driver Supply (+/-5%)	2.50	V
Z_{OUT}	Driver Impedance	20	Ω
R_S	Driver Series Resistor (+/-1%)	294	Ω
R_P	Driver Parallel Resistor (+/-1%)	121	Ω
R_T	Receiver Termination (+/-1%)	100	Ω
V_{OH}	Output High Voltage	1.35	V
V_{OL}	Output Low Voltage	1.15	V
V_{OD}	Output Differential Voltage	0.20	V
V_{CM}	Output Common Mode Voltage	1.25	V
Z_{BACK}	Back Impedance	101.5	Ω
I_{DC}	DC Output Current	3.66	mA

1. For input buffer, see LVDS table.

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

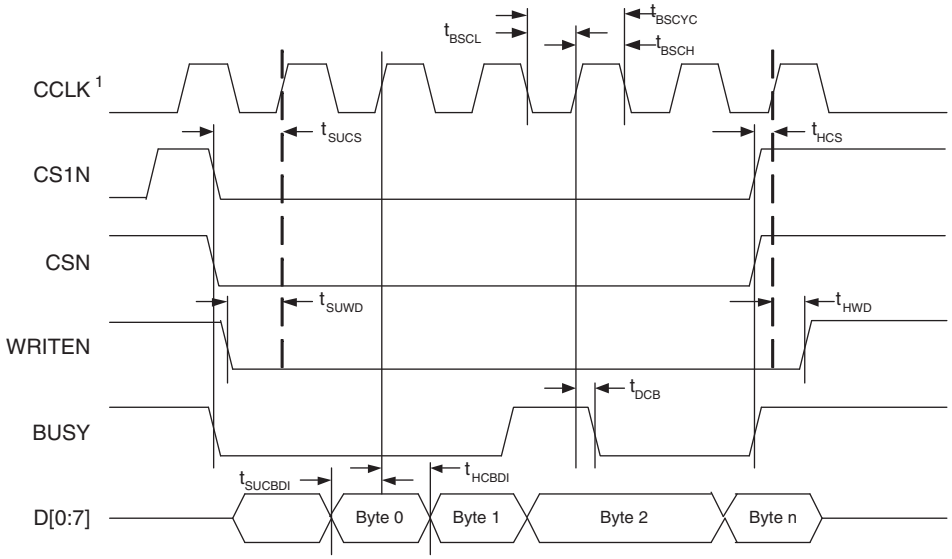
Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{H_DELE}	Clock to Data Hold - PIO Input Register with Input Data Delay	LFE2-6	0.00	—	0.00	—	0.00	—	ns
		LFE2-12	0.00	—	0.00	—	0.00	—	ns
		LFE2-20	0.00	—	0.00	—	0.00	—	ns
		LFE2-35	0.00	—	0.00	—	0.00	—	ns
		LFE2-50	0.00	—	0.00	—	0.00	—	ns
		LFE2-70	0.00	—	0.00	—	0.00	—	ns
		LFE2M20	0.00	—	0.00	—	0.00	—	ns
		LFE2M35	0.00	—	0.00	—	0.00	—	ns
		LFE2M50	0.00	—	0.00	—	0.00	—	ns
		LFE2M70	0.00	—	0.00	—	0.00	—	ns
		LFE2M100	0.00	—	0.00	—	0.00	—	ns
f_{MAX_IOE}	Clock Frequency of I/O and PFU Register	ECP2/M	—	420	—	357	—	311	MHz
General I/O Pin Parameters (using Primary Clock with PLL)[1]									
t_{COPLL}[10]	Clock to Output - PIO Output Register	LFE2-6	—	2.30	—	2.60	—	2.80	ns
		LFE2-12	—	2.30	—	2.60	—	2.80	ns
		LFE2-20	—	2.30	—	2.60	—	2.80	ns
		LFE2-35	—	2.30	—	2.60	—	2.80	ns
		LFE2-50	—	2.30	—	2.60	—	2.80	ns
		LFE2-70	—	2.30	—	2.60	—	2.80	ns
		LFE2M20	—	2.30	—	2.60	—	2.80	ns
		LFE2M35	—	2.30	—	2.60	—	2.80	ns
		LFE2M50	—	2.60	—	2.90	—	3.10	ns
		LFE2M70	—	2.60	—	2.90	—	3.10	ns
		LFE2M100	—	2.70	—	3.00	—	3.20	ns
t_{SUPLL}	Clock to Data Setup - PIO Input Register	LFE2-6	0.70	—	0.80	—	0.90	—	ns
		LFE2-12	0.70	—	0.80	—	0.90	—	ns
		LFE2-20	0.70	—	0.80	—	0.90	—	ns
		LFE2-35	0.70	—	0.80	—	0.90	—	ns
		LFE2-50	0.70	—	0.80	—	0.90	—	ns
		LFE2-70	0.70	—	0.80	—	0.90	—	ns
		LFE2M20	0.70	—	0.80	—	0.90	—	ns
		LFE2M35	0.70	—	0.80	—	0.90	—	ns
		LFE2M50	0.70	—	0.80	—	0.90	—	ns
		LFE2M70	0.70	—	0.80	—	0.90	—	ns
		LFE2M100	0.80	—	0.90	—	1.00	—	ns

LatticeECP2/M sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Byte Data Flow				
t_{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7	—	ns
t_{HCBDI}	Byte D[0:7] Hold Time to CCLK	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
t_{SUCS}	CSN[0:1] Setup Time to CCLK	7	—	ns
t_{HCS}	CSN[0:1] Hold Time to CCLK	1	—	ns
t_{SUWD}	Write Signal Setup Time to CCLK	7	—	ns
t_{HWD}	Write Signal Hold Time to CCLK	1	—	ns
t_{DCB}	CCLK to BUSY Delay Time	—	12	ns
t_{CORD}	CCLK to Out for Read Data	—	12	ns
sysCONFIG Byte Slave Clocking				
t_{BSCH}	Byte Slave CCLK Minimum High Pulse	6	—	ns
t_{BSCL}	Byte Slave CCLK Minimum Low Pulse	9	—	ns
t_{BSCYC}	Byte Slave CCLK Cycle Time	15	—	ns
sysCONFIG Serial (Bit) Data Flow				
t_{SUSCDI}	DI Setup Time to CCLK Slave Mode	7	—	ns
t_{HSCDI}	DI Hold Time to CCLK Slave Mode	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
sysCONFIG Serial Slave Clocking				
t_{SSCH}	Serial Slave CCLK Minimum High Pulse	6	—	ns
t_{SSCL}	Serial Slave CCLK Minimum Low Pulse	6	—	ns
sysCONFIG POR, Initialization and Wake-up				
t_{ICFG}	Minimum Vcc to INITN High	—	28	ms
t_{VMC}	Time from t_{ICFG} to Valid Master CCLK	—	2	us
t_{PRGMRJ}	PROGRAMN Pin Pulse Rejection	—	8	ns
t_{PRGM}	PROGRAMN Low Time to Start Configuration	25	—	ns
t_{DINIT}	PROGRAMN High to INITN High Delay[1]	—	1.5	ms
$t_{DPPINIT}$	Delay Time from PROGRAMN Low to INITN Low	—	37	ns
$t_{DPPDONE}$	Delay Time from PROGRAMN Low to DONE Low	—	37	ns
t_{IODISS}	User I/O Disable from PROGRAMN Low	—	35	ns
t_{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake-up Sequence	—	25	ns
t_{MWC}	Additional Wake Master Clock Signals after DONE Pin High	120	—	cycles
sysCONFIG SPI Port[2]				
t_{CFGX}	INITN High to CCLK Low	—	1	µs
t_{CSSPI}	INITN High to CSSPIN Low	—	2	us
t_{CSCCLK}	CCLK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CCLK Low to Output Valid	—	15	ns
t_{SOE}	CSSPIN[0:1] Active Setup Time	300	—	ns
t_{CSPID}	CSSPIN[0:1] Low to First CCLK Edge Setup Time	300+3cyc	600+6cyc	ns

Figure 3-15. sysCONFIG Parallel Port Write Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-16. sysCONFIG Slave Serial Port Timing

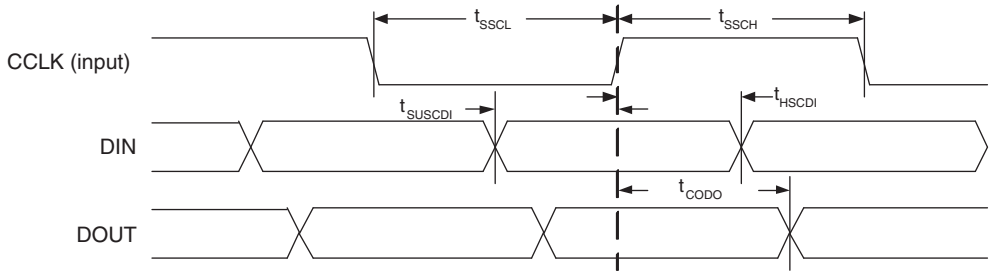
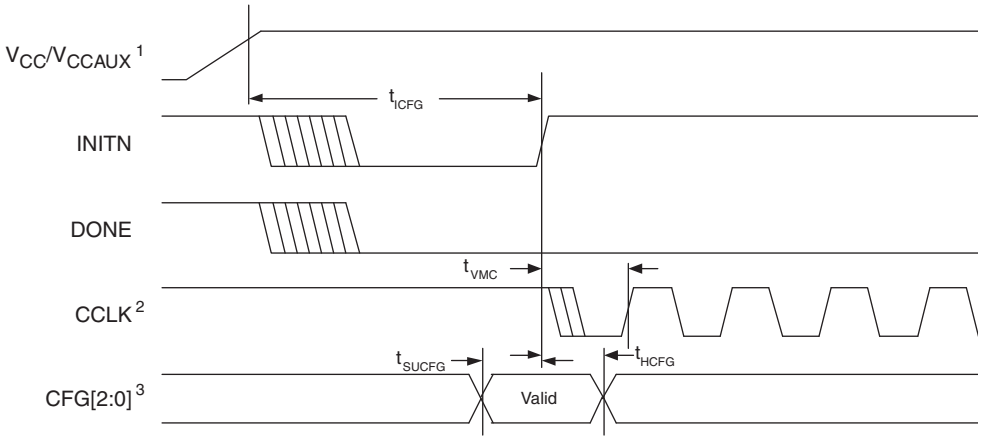


Figure 3-17. Power-On-Reset (POR) Timing



1. Time taken from V_{CC} or V_{CCAUX}, whichever is the last to reach its V_{MIN}.
2. Device is in a Master Mode.
3. The CFG pins are normally static (hard wired).

LatticeECP2M Pin Information Summary, LFE2M20 and LFE2M35

Pin Type		LFE2M20		LFE2M35		
		256 fpBGA	484 fpBGA	256 fpBGA	484 fpBGA	672 fpBGA
Single Ended User I/O		140	304	140	303	410
Differential Pair User I/O		70	152	70	151	199
Configuration	TAP Pins	5	5	5	5	5
	Muxed Pins	14	14	14	14	14
	Dedicated Pins (Non TAP)	7	7	7	7	7
Non Configuration	Muxed Pins	64	84	60	84	89
	Dedicated Pins	3	3	3	3	3
VCC		6	16	6	16	29
VCCAUX		4	8	4	8	17
VCCPLL		1	4	1	4	8
VCCIO	Bank0	1	4	1	4	5
	Bank1	1	3	1	3	4
	Bank2	2	4	2	4	5
	Bank3	2	4	2	4	5
	Bank4	2	4	2	4	4
	Bank5	2	4	2	4	5
	Bank6	2	4	2	4	5
	Bank7	2	4	2	4	5
	Bank8	1	2	1	2	2
GND, GND0 to GND7		22	57	22	57	80
NC		17	11	17	12	37
Single Ended/ Differential I/O Pairs per Bank (including emulated with resistors)	Bank0	0/0	36/18	0/0	36/18	63/31
	Bank1	0/0	18/9	0/0	18/9	18/9
	Bank2	14/7	30/15	14/7	30/15	50/25
	Bank3	16/8	36/18	16/8	36/18	43/21
	Bank4	32/16	62/31	32/16	62/31	50/21
	Bank5	20/10	28/14	20/10	28/14	60/30
	Bank6	16/8	40/20	16/8	39/19	52/25
	Bank7	28/14	40/20	28/14	40/20	60/30
	Bank8	14/7	14/7	14/7	14/7	14/7
True LVDS I/O Pairs per Bank	Bank0 (Top Edge)	0	0	0	0	0
	Bank1 (Top Edge)	0	0	0	0	0
	Bank2 (Right Edge)	3	7	3	7	12
	Bank3 (Right Edge)	4	9	4	9	11
	Bank4 (Bottom Edge)	0	0	0	0	0
	Bank5 (Bottom Edge)	0	0	0	0	0
	Bank6 (Left Edge)	4	10	4	10	14
	Bank7 (Left Edge)	7	10	7	10	15
	Bank8 (Right Edge)	0	0	0	0	0

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-6E/SE					LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N14	CFG1	8			CFG1	8		
N13	PROGRAMN	8			PROGRAMN	8		
N15	CFG0	8			CFG0	8		
P15	PR30B	8	WRITEN	C	PR30B	8	WRITEN	C
L12	INITN	8			INITN	8		
N16	PR29B	8	CSN	C	PR29B	8	CSN	C
GND	GNDIO8	-			GNDIO8	-		
R14	CCLK	8			CCLK	8		
P14	PR30A	8	CS1N	T	PR30A	8	CS1N	T
M13	DONE	8			DONE	8		
R16	PR28B	8	D1	C	PR28B	8	D1	C
VCCIO	VCCIO8	8			VCCIO8	8		
M16	PR29A	8	D0/SPIFASTN	T	PR29A	8	D0/SPIFASTN	T
P16	PR28A	8	D2	T	PR28A	8	D2	T
L15	PR27B	8	D3	C	PR27B	8	D3	C
GND	GNDIO8	-			GNDIO8	-		
L14	PR26A	8	D6	T	PR26A	8	D6	T
L16	PR27A	8	D4	T	PR27A	8	D4	T
L10	PR25B	8	D7/SPID0	C	PR25B	8	D7/SPID0	C
L13	PR26B	8	D5	C	PR26B	8	D5	C
VCCIO	VCCIO8	8			VCCIO8	8		
K11	PR25A	8	DI/CSSPI0N	T	PR25A	8	DI/CSSPI0N	T
K14	PR24B	8	DOUT/CSON	C	PR24B	8	DOUT/CSON	C
K13	PR24A	8	BUSY/SISPI	T	PR24A	8	BUSY/SISPI	T
GND	GNDIO8	-			GNDIO8	-		
K15	PR21B	3	RLM0_GPLLC_FB_A	C	PR21B	3	RLM0_GPLLC_FB_A	C
VCCIO	VCCIO3	3			VCCIO3	3		
K16	PR21A	3	RLM0_GPLLT_FB_A	T	PR21A	3	RLM0_GPLLT_FB_A	T
GND	GNDIO3	-			GNDIO3	-		
J16	PR20B	3	RLM0_GPLLC_IN_A**	C (LVDS)*	PR20B	3	RLM0_GPLLC_IN_A**	C (LVDS)*
J15	PR20A	3	RLM0_GPLLT_IN_A**	T (LVDS)*	PR20A	3	RLM0_GPLLT_IN_A**	T (LVDS)*
J14	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
J13	PR18B	3	RLM0_GDLLC_FB_A	C	PR18B	3	RLM0_GDLLC_FB_A	C
J12	PR18A	3	RLM0_GDLLT_FB_A	T	PR18A	3	RLM0_GDLLT_FB_A	T
H12	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*
GND	GNDIO3	-			GNDIO3	-		
H13	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*
H15	PR16B	3	VREF2_3	C	PR16B	3	VREF2_3	C
VCCIO	VCCIO3	3			VCCIO3	3		
H16	PR16A	3	VREF1_3	T	PR16A	3	VREF1_3	T
H11	PR15B	3	PCLKC3_0	C (LVDS)*	PR15B	3	PCLKC3_0	C (LVDS)*
J11	PR15A	3	PCLKT3_0	T (LVDS)*	PR15A	3	PCLKT3_0	T (LVDS)*
G16	PR13B	2	PCLKC2_0/RDQ10	C	PR13B	2	PCLKC2_0/RDQ10	C
GND	GNDIO2	-			GNDIO2	-		
G15	PR13A	2	PCLKT2_0/RDQ10	T	PR13A	2	PCLKT2_0/RDQ10	T

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
W5	PL38B	6	LDQ42	C (LVDS)*	PL52B	6	LDQ56	C (LVDS)*
AC1	PL39A	6	LDQ42	T	PL53A	6	LDQ56	T
AD1	PL39B	6	LDQ42	C	PL53B	6	LDQ56	C
VCCIO	VCCIO6	6			VCCIO6	6		
Y6	PL40A	6	LDQ42	T (LVDS)*	PL54A	6	LDQ56	T (LVDS)*
Y5	PL40B	6	LDQ42	C (LVDS)*	PL54B	6	LDQ56	C (LVDS)*
AE2	PL41A	6	LDQ42	T	PL55A	6	LDQ56	T
AD2	PL41B	6	LDQ42	C	PL55B	6	LDQ56	C
GND	GNDIO6	-			GNDIO6	-		
AB3	PL42A	6	LDQS42	T (LVDS)*	PL56A	6	LDQS56	T (LVDS)*
AB2	PL42B	6	LDQ42	C (LVDS)*	PL56B	6	LDQ56	C (LVDS)*
W7	PL43A	6	LDQ42	T	PL57A	6	LDQ56	T
VCCIO	VCCIO6	6			VCCIO6	6		
W8	PL43B	6	LDQ42	C	PL57B	6	LDQ56	C
Y7	PL44A	6	LDQ42	T (LVDS)*	PL58A	6	LDQ56	T (LVDS)*
Y8	PL44B	6	LDQ42	C (LVDS)*	PL58B	6	LDQ56	C (LVDS)*
AC2	PL45A	6	LDQ42	T	PL59A	6	LDQ56	T
GND	GNDIO6	-			GNDIO6	-		
AD3	PL45B	6	LDQ42	C	PL59B	6	LDQ56	C
AC3	TCK	-			TCK	-		
AA8	TDI	-			TDI	-		
AB4	TMS	-			TMS	-		
AA5	TDO	-			TDO	-		
AB5	VCCJ	-			VCCJ	-		
AE3	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T
AF3	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C
AC4	PB3A	5	BDQ6	T	PB3A	5	BDQ6	T
AD4	PB3B	5	BDQ6	C	PB3B	5	BDQ6	C
AE4	PB4A	5	BDQ6	T	PB4A	5	BDQ6	T
AF4	PB4B	5	BDQ6	C	PB4B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
V9	PB5A	5	BDQ6	T	PB5A	5	BDQ6	T
W9	PB5B	5	BDQ6	C	PB5B	5	BDQ6	C
GND	GNDIO5	-			GNDIO5	-		
AA6	PB6A	5	BDQS6	T	PB6A	5	BDQS6	T
AB6	PB6B	5	BDQ6	C	PB6B	5	BDQ6	C
AC5	PB7A	5	BDQ6	T	PB7A	5	BDQ6	T
AD5	PB7B	5	BDQ6	C	PB7B	5	BDQ6	C
AA7	PB8A	5	BDQ6	T	PB8A	5	BDQ6	T
AB7	PB8B	5	BDQ6	C	PB8B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
AE5	PB9A	5	BDQ6	T	PB9A	5	BDQ6	T
AF5	PB9B	5	BDQ6	C	PB9B	5	BDQ6	C
AC7	PB10A	5	BDQ6	T	PB10A	5	BDQ6	T
AD7	PB10B	5	BDQ6	C	PB10B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C20	PT57B	1		C	PT66B	1		C
D20	PT57A	1		T	PT66A	1		T
A22	PT56B	1		C	PT65B	1		C
A21	PT56A	1		T	PT65A	1		T
GND	GNDIO1	-			GNDIO1	-		
E19	NC	-			NC	-		
C19	NC	-			NC	-		
VCCIO	VCCIO1	1			VCCIO1	1		
B21	NC	-			NC	-		
B20	NC	-			NC	-		
D19	NC	-			NC	-		
B19	NC	-			NC	-		
GND	GNDIO1	-			GNDIO1	-		
G17	NC	-			NC	-		
E18	NC	-			NC	-		
G19	NC	-			NC	-		
F17	NC	-			NC	-		
VCCIO	VCCIO1	1			VCCIO1	1		
A20	NC	-			NC	-		
A19	NC	-			NC	-		
E17	NC	-			NC	-		
D18	NC	-			NC	-		
B18	PT55B	1		C	PT55B	1		C
GND	GNDIO1	-			GNDIO1	-		
A18	PT55A	1		T	PT55A	1		T
E16	PT54B	1		C	PT54B	1		C
G16	PT54A	1		T	PT54A	1		T
F16	PT53B	1		C	PT53B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
H18	PT53A	1		T	PT53A	1		T
A17	PT52B	1		C	PT52B	1		C
B17	PT52A	1		T	PT52A	1		T
C18	PT51B	1		C	PT51B	1		C
B16	PT51A	1		T	PT51A	1		T
C17	PT50B	1		C	PT50B	1		C
GND	GNDIO1	-			GNDIO1	-		
D17	PT50A	1		T	PT50A	1		T
E15	PT49B	1		C	PT49B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
G15	PT49A	1		T	PT49A	1		T
A16	PT48B	1		C	PT48B	1		C
B15	PT48A	1		T	PT48A	1		T
D15	PT47B	1		C	PT47B	1		C
F15	PT47A	1		T	PT47A	1		T
A14	PT46B	1		C	PT46B	1		C
B14	PT46A	1		T	PT46A	1		T

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A7	PT26B	0		C	PT26B	0		C
B7	PT26A	0		T	PT26A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F12	PT25B	0		C	PT25B	0		C
D10	PT25A	0		T	PT25A	0		T
H11	PT24B	0		C	PT24B	0		C
G11	PT24A	0		T	PT24A	0		T
GND	GNDIO0	-			GNDIO0	-		
A6	PT23B	0		C	PT23B	0		C
B6	PT23A	0		T	PT23A	0		T
D8	PT22B	0		C	PT22B	0		C
C8	PT22A	0		T	PT22A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F11	PT21B	0		C	PT21B	0		C
E10	PT21A	0		T	PT21A	0		T
E9	PT20B	0		C	PT20B	0		C
D9	PT20A	0		T	PT20A	0		T
G10	PT19B	0		C	PT19B	0		C
GND	GNDIO0	-			GNDIO0	-		
H10	PT19A	0		T	PT19A	0		T
A5	PT18B	0		C	PT18B	0		C
B5	PT18A	0		T	PT18A	0		T
C7	PT17B	0		C	PT17B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
D7	PT17A	0		T	PT17A	0		T
E8	PT16B	0		C	PT16B	0		C
F10	PT16A	0		T	PT16A	0		T
F8	PT15B	0		C	PT15B	0		C
H9	PT15A	0		T	PT15A	0		T
C5	PT14B	0		C	PT14B	0		C
GND	GNDIO0	-			GNDIO0	-		
D5	PT14A	0		T	PT14A	0		T
B4	PT13B	0			PT13B	0		
VCCIO	VCCIO0	0			VCCIO0	0		
GND	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
GND	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
C4	PT10B	0		C	PT10B	0		C
GND	GNDIO0	-			GNDIO0	-		
C3	PT10A	0		T	PT10A	0		T
A4	PT9B	0		C	PT9B	0		C
A3	PT9A	0		T	PT9A	0		T
B3	PT8B	0		C	PT8B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
B2	PT8A	0		T	PT8A	0		T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA14	PB38B	5	BDQ42	C	PB47B	5	BDQ51	C
AE10	PB39A	5	BDQ42	T	PB48A	5	BDQ51	T
AF10	PB39B	5	BDQ42	C	PB48B	5	BDQ51	C
W14	PB40A	5	BDQ42	T	PB49A	5	BDQ51	T
AB13	PB40B	5	BDQ42	C	PB49B	5	BDQ51	C
VCCIO	VCCIO5	5			VCCIO5	5		
Y14	PB41A	5	BDQ42	T	PB50A	5	BDQ51	T
AB14	PB41B	5	BDQ42	C	PB50B	5	BDQ51	C
GND	GNDIO5	-			GNDIO5	-		
AE11	PB42A	5	BDQS42	T	PB51A	5	BDQS51	T
AF11	PB42B	5	BDQ42	C	PB51B	5	BDQ51	C
AD14	PB43A	5	BDQ42	T	PB52A	5	BDQ51	T
AA15	PB43B	5	BDQ42	C	PB52B	5	BDQ51	C
AE12	PB44A	5	PCLKT5_0/BDQ42	T	PB53A	5	PCLKT5_0/BDQ51	T
AF12	PB44B	5	PCLKC5_0/BDQ42	C	PB53B	5	PCLKC5_0/BDQ51	C
VCCIO	VCCIO5	5			VCCIO5	5		
GND	GNDIO5	-			GNDIO5	-		
AD15	PB49A	4	PCLKT4_0/BDQ51	T	PB58A	4	PCLKT4_0/BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
AC15	PB49B	4	PCLKC4_0/BDQ51	C	PB58B	4	PCLKC4_0/BDQ60	C
AE13	PB50A	4	BDQ51	T	PB59A	4	BDQ60	T
AF13	PB50B	4	BDQ51	C	PB59B	4	BDQ60	C
AB17	PB51A	4	BDQS51	T	PB60A	4	BDQS60	T
GND	GNDIO4	-			GNDIO4	-		
Y15	PB51B	4	BDQ51	C	PB60B	4	BDQ60	C
AE14	PB52A	4	BDQ51	T	PB61A	4	BDQ60	T
AF14	PB52B	4	BDQ51	C	PB61B	4	BDQ60	C
AA16	PB53A	4	BDQ51	T	PB62A	4	BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
W15	PB53B	4	BDQ51	C	PB62B	4	BDQ60	C
AC17	PB54A	4	BDQ51	T	PB63A	4	BDQ60	T
AB16	PB54B	4	BDQ51	C	PB63B	4	BDQ60	C
AE15	PB55A	4	BDQ51	T	PB64A	4	BDQ60	T
GND	GNDIO4	-			GNDIO4	-		
AF15	PB55B	4	BDQ51	C	PB64B	4	BDQ60	C
AE16	PB56A	4	BDQ60	T	PB65A	4	BDQ69	T
AF16	PB56B	4	BDQ60	C	PB65B	4	BDQ69	C
Y16	PB57A	4	BDQ60	T	PB66A	4	BDQ69	T
AB18	PB57B	4	BDQ60	C	PB66B	4	BDQ69	C
AD17	PB58A	4	BDQ60	T	PB67A	4	BDQ69	T
AD18	PB58B	4	BDQ60	C	PB67B	4	BDQ69	C
VCCIO	VCCIO4	4			VCCIO4	4		
AC18	PB59A	4	BDQ60	T	PB68A	4	BDQ69	T
AD19	PB59B	4	BDQ60	C	PB68B	4	BDQ69	C
GND	GNDIO4	-			GNDIO4	-		
AC19	PB60A	4	BDQS60	T	PB69A	4	BDQS69	T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
G24	PR14B	2	RDQ16	C (LVDS)*	PR27B	2	RDQ29	C (LVDS)*
G23	PR14A	2	RDQ16	T (LVDS)*	PR27A	2	RDQ29	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
K19	PR13B	2	RDQ16	C	PR26B	2	RDQ29	C
J19	PR13A	2	RDQ16	T	PR26A	2	RDQ29	T
D26	PR12B	2	RDQ16	C (LVDS)*	PR25B	2	RDQ29	C (LVDS)*
C26	PR12A	2	RDQ16	T (LVDS)*	PR25A	2	RDQ29	T (LVDS)*
F22	PR11B	2	RDQ8	C	PR24B	2	RDQ21	C
E24	PR11A	2	RDQ8	T	PR24A	2	RDQ21	T
GND	GNDIO2	-			GNDIO2	-		
D25	PR10B	2	RDQ8	C (LVDS)*	PR23B	2	RDQ21	C (LVDS)*
C25	PR10A	2	RDQ8	T (LVDS)*	PR23A	2	RDQ21	T (LVDS)*
D24	PR9B	2	RDQ8	C	PR22B	2	RDQ21	C
B25	PR9A	2	RDQ8	T	PR22A	2	RDQ21	T
VCCIO	VCCIO2	2			VCCIO2	2		
H21	PR8B	2	RDQ8	C (LVDS)*	PR21B	2	RDQ21	C (LVDS)*
G22	PR8A	2	RDQS8	T (LVDS)*	PR21A	2	RDQS21	T (LVDS)*
B24	PR7B	2	RDQ8	C	PR20B	2	RDQ21	C
GND	GNDIO2	-			GNDIO2	-		
C24	PR7A	2	RDQ8	T	PR20A	2	RDQ21	T
D23	PR6B	2	RDQ8	C (LVDS)*	PR19B	2	RDQ21	C (LVDS)*
C23	PR6A	2	RDQ8	T (LVDS)*	PR19A	2	RDQ21	T (LVDS)*
G21	PR5B	2	RDQ8	C	PR18B	2	RDQ21	C
VCCIO	VCCIO2	2			VCCIO2	2		
H20	PR5A	2	RDQ8	T	PR18A	2	RDQ21	T
GND	GNDIO2	-			GNDIO2	-		
E22	PR2B	2	VREF2_2	C (LVDS)*	PR2B	2	VREF2_2	C (LVDS)*
F21	PR2A	2	VREF1_2	T (LVDS)*	PR2A	2	VREF1_2	T (LVDS)*
E23	PT82B	1	VREF2_1	C	PT100B	1	VREF2_1	C
GND	GNDIO1	-			GNDIO1	-		
D22	PT82A	1	VREF1_1	T	PT100A	1	VREF1_1	T
G20	PT81B	1		C	PT99B	1		C
J18	PT81A	1		T	PT99A	1		T
F20	PT80B	1		C	PT98B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
H19	PT80A	1		T	PT98A	1		T
A24	PT79B	1		C	PT97B	1		C
A23	PT79A	1		T	PT97A	1		T
E21	PT78B	1		C	PT96B	1		C
F19	PT78A	1		T	PT96A	1		T
C22	PT77B	1		C	PT95B	1		C
GND	GNDIO1	-			GNDIO1	-		
E20	PT77A	1		T	PT95A	1		T
B22	PT76B	1		C	PT94B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
B23	PT76A	1		T	PT94A	1		T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N15	GND	-			GND	-		
N17	GND	-			GND	-		
P10	GND	-			GND	-		
P12	GND	-			GND	-		
P13	GND	-			GND	-		
P14	GND	-			GND	-		
P15	GND	-			GND	-		
P17	GND	-			GND	-		
R13	GND	-			GND	-		
R14	GND	-			GND	-		
T10	GND	-			GND	-		
T11	GND	-			GND	-		
T16	GND	-			GND	-		
T17	GND	-			GND	-		
T24	GND	-			GND	-		
T3	GND	-			GND	-		
U10	GND	-			GND	-		
U11	GND	-			GND	-		
U13	GND	-			GND	-		
U14	GND	-			GND	-		
U16	GND	-			GND	-		
U17	GND	-			GND	-		
V13	GND	-			GND	-		
V14	GND	-			GND	-		
V21	GND	-			GND	-		
V6	GND	-			GND	-		
M3	NC	-			NC	-		
N6	NC	-			NC	-		
P24	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE Logic Signal Connections: 484 fpBGA

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
D1	PL2A	7	LDQ6	T (LVDS)*
E1	PL2B	7	LDQ6	C (LVDS)*
F1	PL3A	7	LDQ6	T
F2	PL3B	7	LDQ6	C
F5	PL4A	7	LDQ6	T (LVDS)*
VCCIO	VCCIO7	7		
G6	PL4B	7	LDQ6	C (LVDS)*
F4	PL5A	7	LDQ6	T
F3	PL5B	7	LDQ6	C
G1	PL6A	7	LDQS6	T (LVDS)*
GNDIO	GNDIO7	-		
G2	PL6B	7	LDQ6	C (LVDS)*
H1	PL7A	7	LDQ6	T
H2	PL7B	7	LDQ6	C
VCCIO	VCCIO7	7		
H7	PL8A	7	LDQ6	T (LVDS)*
H6	PL8B	7	LDQ6	C (LVDS)*
G3	PL9A	7	VREF2_7/LDQ6	T
H3	PL9B	7	VREF1_7/LDQ6	C
GNDIO	GNDIO7	-		
VCCIO	VCCIO7	7		
H5	PL11A	7	LUM0_SPLLT_IN_A	T (LVDS)*
H4	PL11B	7	LUM0_SPLLC_IN_A	C (LVDS)*
J1	PL12A	7	LUM0_SPLLT_FB_A	T
J2	PL12B	7	LUM0_SPLLC_FB_A	C
GNDIO	GNDIO7	-		
J3	PL13A	7		T (LVDS)*
J4	PL13B	7		C (LVDS)*
J7	PL14A	7		T
VCCIO	VCCIO7	7		
J6	PL14B	7		C
GNDIO	GNDIO7	-		
VCCIO	VCCIO7	7		
K1	PL32A	7	LUM3_SPLLT_IN_A/LDQ36	T (LVDS)*
K2	PL32B	7	LUM3_SPLLC_IN_A/LDQ36	C (LVDS)*
J5	PL33A	7	LUM3_SPLLT_FB_A/LDQ36	T
K5	PL33B	7	LUM3_SPLLC_FB_A/LDQ36	C
VCCIO	VCCIO7	7		
K7	PL34A	7	LDQ36	T (LVDS)*
K6	PL34B	7	LDQ36	C (LVDS)*
L6	PL35A	7	LDQ36	T
L7	PL35B	7	LDQ36	C

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
F20	PR30A	2	RDQ27	T
GNDIO	GNDIO2	-		
G17	PR29B	2	RDQ27	C (LVDS)*
F17	PR29A	2	RDQ27	T (LVDS)*
VCCIO	VCCIO2	2		
GNDIO	GNDIO2	-		
E22	PR14B	2		C
D22	PR14A	2		T
VCCIO	VCCIO2	-		
E20	PR13B	2		C (LVDS)*
D20	PR13A	2		T (LVDS)*
D19	PR12B	2	RUM0_SPLLC_FB_A	C
GNDIO	GNDIO2	-		
E19	PR12A	2	RUM0_SPLLT_FB_A	T
F18	PR11B	2	RUM0_SPLLC_IN_A	C (LVDS)*
F19	PR11A	2	RUM0_SPLLT_IN_A	T (LVDS)*
VCCIO	VCCIO2	-		
E18	PR9B	2	VREF2_2	C
GNDIO	GNDIO2	-		
D18	PR9A	2	VREF1_2	T
VCCIO	VCCIO2	2		
F16	XRES	-		
C22	URC_SQ_VCCRX0	12		
A21	URC_SQ_HDINP0	12		T
B22	URC_SQ_VCCIB0	12		
B21	URC_SQ_HDINN0	12		C
C19	URC_SQ_VCCTX0	12		
A18	URC_SQ_HDOUTP0	12		T
A19	URC_SQ_VCCOB0	12		
B18	URC_SQ_HDOUTN0	12		C
C18	URC_SQ_VCCTX1	12		
B17	URC_SQ_HDOUTN1	12		C
C17	URC_SQ_VCCOB1	12		
A17	URC_SQ_HDOUTP1	12		T
C21	URC_SQ_VCCRX1	12		
B20	URC_SQ_HDINN1	12		C
C20	URC_SQ_VCCIB1	12		
A20	URC_SQ_HDINP1	12		T
B16	URC_SQ_VCCAUX33	12		
E17	URC_SQ_REFCLKN	12		C
D17	URC_SQ_REFCLKP	12		T
C16	URC_SQ_VCCP	12		
A12	URC_SQ_HDINP2	12		T

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
J11	VCC	-		
J12	VCC	-		
J13	VCC	-		
K14	VCC	-		
K9	VCC	-		
L14	VCC	-		
L9	VCC	-		
M14	VCC	-		
M9	VCC	-		
N14	VCC	-		
N9	VCC	-		
P10	VCC	-		
P11	VCC	-		
P12	VCC	-		
P13	VCC	-		
B5	VCCIO0	0		
B9	VCCIO0	0		
E7	VCCIO0	0		
H9	VCCIO0	0		
D13	VCCIO1	1		
E16	VCCIO1	1		
H14	VCCIO1	1		
E21	VCCIO2	2		
G18	VCCIO2	2		
J15	VCCIO2	2		
K19	VCCIO2	2		
N19	VCCIO3	3		
P15	VCCIO3	3		
T18	VCCIO3	3		
V21	VCCIO3	3		
AA18	VCCIO4	4		
R14	VCCIO4	4		
V16	VCCIO4	4		
W13	VCCIO4	4		
AA5	VCCIO5	5		
R9	VCCIO5	5		
V7	VCCIO5	5		
W10	VCCIO5	5		
N4	VCCIO6	6		
P8	VCCIO6	6		
T5	VCCIO6	6		
V2	VCCIO6	6		
E2	VCCIO7	7		

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
L16	GND	-			GND	-		
L17	GND	-			GND	-		
L2	GND	-			GND	-		
L20	GND	-			GND	-		
L25	GND	-			GND	-		
L7	GND	-			GND	-		
M13	GND	-			GND	-		
M14	GND	-			GND	-		
N10	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N14	GND	-			GND	-		
N15	GND	-			GND	-		
N17	GND	-			GND	-		
P10	GND	-			GND	-		
P12	GND	-			GND	-		
P13	GND	-			GND	-		
P14	GND	-			GND	-		
P15	GND	-			GND	-		
P17	GND	-			GND	-		
R13	GND	-			GND	-		
R14	GND	-			GND	-		
T10	GND	-			GND	-		
T11	GND	-			GND	-		
T16	GND	-			GND	-		
T17	GND	-			GND	-		
T2	GND	-			GND	-		
T20	GND	-			GND	-		
T25	GND	-			GND	-		
T7	GND	-			GND	-		
U11	GND	-			GND	-		
U13	GND	-			GND	-		
U14	GND	-			GND	-		
U16	GND	-			GND	-		
V22	GND	-			GND	-		
V5	GND	-			GND	-		
Y11	GND	-			GND	-		
Y16	GND	-			GND	-		
AB3	NC	-			NC	-		
AB4	NC	-			NC	-		
AC1	NC	-			NC	-		
AC2	NC	-			NC	-		
B4	NC	-			NC	-		
B5	NC	-			NC	-		
C26	NC	-			NC	-		
D20	NC	-			NC	-		
D21	NC	-			NC	-		
D22	NC	-			NC	-		

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVCMOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
			Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
April 2008	03.1	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
June 2008	03.2	Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Clarification of the operation of the secondary clock regions.
		DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
August 2008	03.3	Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPIm Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t_{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.